PCN Number:	20160317001	**PCN Date:**	03/21/2016
Title:	TUSB9261xPVPx Die Revision Change		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	06/21/2016	**Estimated Sample Availability:**	Date provided at sample request.
Change Type:			

☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☒	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

This notification is to inform of a design change to select devices. The design changes do not affect the device's guaranteed datasheet specifications or electrical performance. Affected devices are listed in "Product Affected" section. Design changes as follows:

TUSB9261xPVPx Die Rev Change (Rev B to Rev C): The die change is for manufacturing optimization and harmonization across the TUSB9261x family

Reason for Change:

Improved product performance

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Die Rev designator will change as shown in the table and sample label below:

Current	**New**
Die Rev [2P]	**Die Rev [2P]**
B	**C**

Sample product shipping label (not actual product label)

Product Affected:

TUSB9261IPVP	TUSB9261IPVPT	TUSB9261PVPR	TUSB9261PVPT
TUSB9261IPVPR	TUSB9261PVP		

Qualification Report

TUSB9261PVP and TUSB9261IPVP with New Die Rev
Approve Date 08-Feb-2016

Product Attributes

Attributes	Qual Device: TUSB9261IPVP	QBS Product Reference: TUSB9261IPAPRQ1_FINAL	QBS Product Reference: TUSB9261IPAPRQ1_REV1	QBS Process Reference: TUSB1310ZAY_1.0	QBS Package Reference: SH6960BEA0PAPG4	QBS Package Reference: TAS5709PHP
Assembly Site	PHI	PHI	PHI	PHI	PHI	PHI
Package Family	HTQFP	HTQFP	HTQFP	nfBGA	HTQFP	HTQFP
Wafer Fab Supplier	DMOS6	DMOS6	DMOS6	DMOS6	MIHO8	DMOS5
Wafer Process	1118C021.A7	1118C021.A7	1118C021.A7	1118C021.A7	LBC6	1833C05X4, LBC5X

- QBS: Qual by Similarity
- Qual Device TUSB9261IPVP is qualified at LEVEL3-260C

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TUSB9261IPVP	QBS Product Reference: TUSB9261IPAPRQ1_FINAL	QBS Product Reference: TUSB9261IPAPRQ1_REV1	QBS Process Reference: TUSB1310ZAY_1.0	QBS Package Reference: SH6960BEA0PAPG4	QBS Package Reference: TAS5709PHP
AC	Autoclave 121C	96 Hours	-	3/231/0	-	-	3/231/0	3/230/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	-	-	-	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	3/2399/0	-	3/1838/1 **(1)**	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	-	3/231/0	3/231/0	-
HBM	ESD - HBM	2000 V	1/3/0	-	-	-	-	-
CDM	ESD - CDM	1500 V	1/3/0	-	-	-	-	-
HTOL	Life Test, 125C	1000 Hours	-	-	1/77/0	3/231/0	3/231/0	-
HTSL	High Temp. StorageBake, 150C	1000 Hours	-	2/154/0	-	3/227/0	-	-
HTSL	High Temp. StorageBake, 170C	420 Hours	-	-	-	-	3/231/0	-
LU	Latch-up	(per JESD78)	1/6/0	-	-	3/18/0	-	-
SD	Surface Mount Solderability	Pb Free	-	-	-	-	-	3/66/0
TC	Temperature Cycle, -55/125C	700 Cycles	-	-	-	3/231/0	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	-	-	3/231/0	3/231/0
TS	Thermal Shock -65/150C	500 Cycles	-	3/231/0	-	-	3/231/0	-
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	-	-	3/231/0	-	-
WBP	Bond Pull	Wires	-	3/231/0	-	1/76/0	-	2/152/0
WBS	Ball Bond Shear	Wires	-	3/231/0	-	1/76/0	-	2/152/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:
Qualified Pb-Free (SMT) and Green

Notes:

1.) Fail not silicon related. Assembly related defect

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com